

# LV10T150D

Rev.F May.-2016

## / Descriptions

TO-252

Schottky Barrier Diode in a TO-252 Plastic Package.

## / Features

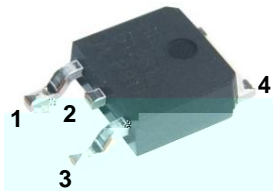
High Forward Surge Capability, Ultra Low Forward Voltage Drop, Excellent High Temperature Stability.

## / Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

## / Equivalent Circuit

## / Pinning



PIN1 Anode

PIN 2,4 Cathode

PIN 3 Anode

## / $h_{FE}$ Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings( $T_a=25$  )

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_{RM}$	150	V
RMS Reverse Voltage	$V_{R(RMS)}$	105	V
Average Forward Rectified Current	$I_{F(AV)}$	10	A
Peak Forward Surge Current	$I_{FSM}$	200	A
Typical Thermal Resistance Junction to Case	$R_{Jc}$	6.5	/W
Junction Temperature Range	$T_{jMAX}$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

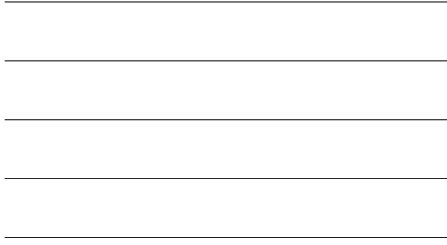
/ Electrical Characteristics( $T_a=25$  )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{BR}$	$I_R=0.3mA$	150			V
Forward Voltage	$V_F$	$I_F=2A$ $T_J=25$		0.57	0.60	V
		$I_F=2A$ $T_J=125$		0.47	0.55	V
		$I_F=10A$ $T_J=25$		0.81	0.85	V
		$I_F=10A$ $T_J=125$		0.69	0.75	V
Instantaneous Reverse Current	$I_R$ Note 1	$V_R=100V$ $T_J=25$		5	50	$\mu A$
		$V_R=100V$ $T_J=100$			10	mA
		$V_R=100V$ $T_J=125$			20	mA

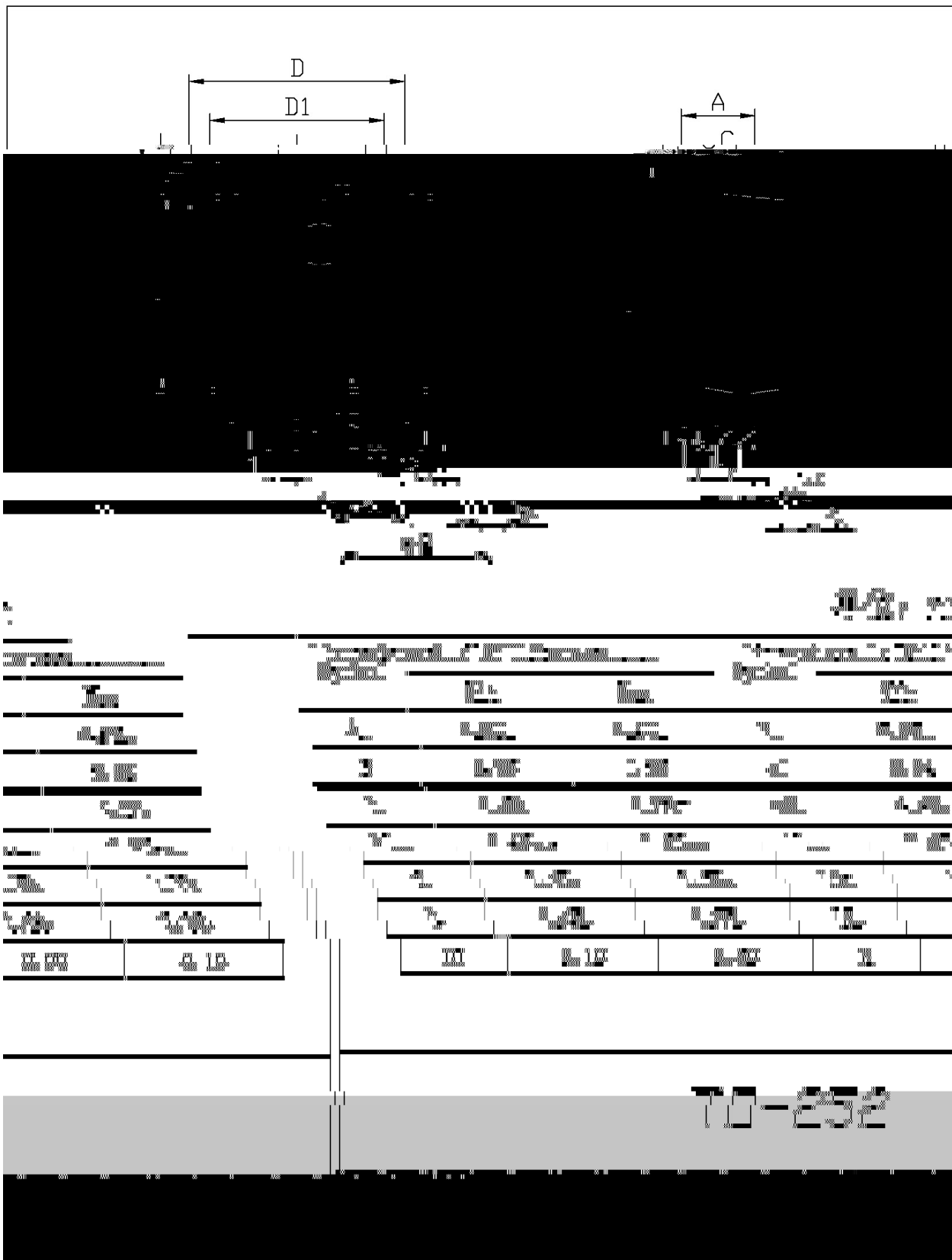
/Notes

1. /Short duration pulse test used to minimize self-heating effect.

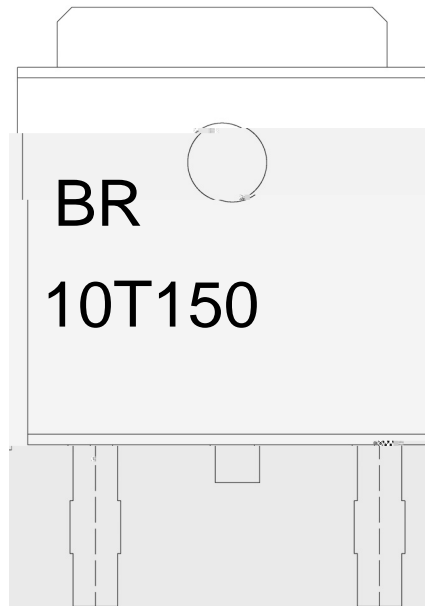
/ **Electrical Characteristic Curve**



/ Package Dimensions



/ Marking Instructions



BR

10T150

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Note:

BR:

Company Code

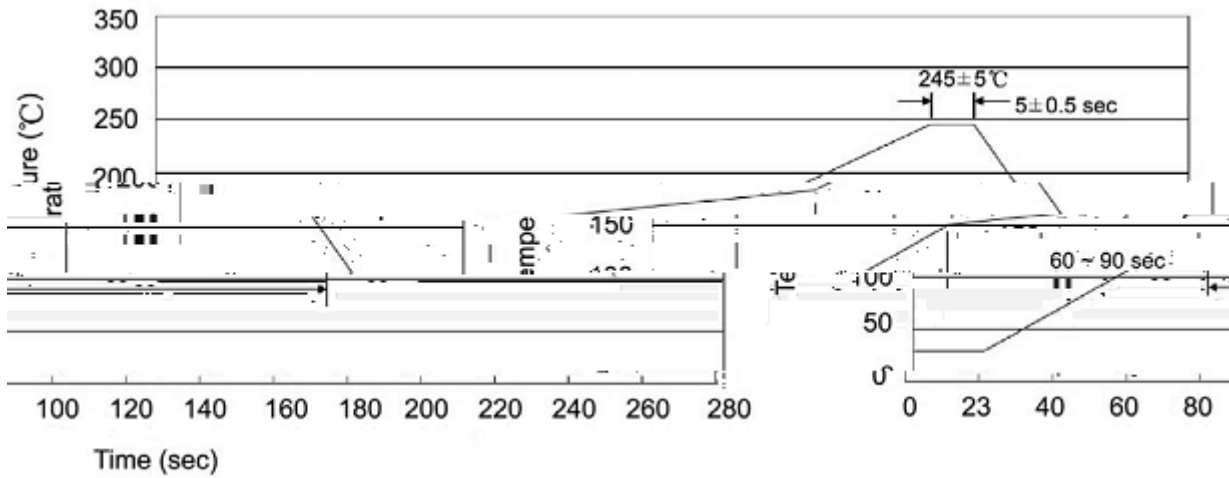
10T150

Product Type Code.

\*\*\*\*:

Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |           |        |   |
|---|-------|-----|-----------|--------|---|
| 1 | 25    | 150 | 60        | 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     | 5±0.5sec; |        | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10        | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		